This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

- 1 1. (currently amended): A magnetic head comprising:
- a write head portion including a first magnetic pole and a second magnetic pole;
- an induction coil being disposed at least in part between said first and second magnetic
- 4 poles;
- 5 an electrical lead of said induction coil having an electrical lead thickness and being
- 6 disposed in a layer of the magnetic head;
- a heat sink being disposed within said layer and being coplanar within the magnetic head
- 8 with said electrical lead of said coil, said heat sink having a heat sink thickness that is equal to
- 9 said electrical lead thickness.
- 1 2. (original): A magnetic head as described in claim 1 wherein said electrical lead is
- 2 comprised of copper and said heat sink is comprised of copper.
- 1 3. (currently amended): A magnetic head as described in claim 1 wherein said heat sink is
- 2 disposed at least in part <u>directly</u> upon said second magnetic pole.
- 1 4. (original): A magnetic head as described in claim 1 wherein said electrical lead is
- 2 fabricated upon an insulation layer that is disposed in part above said second magnetic pole, and
- 3 wherein said heat sink is fabricated upon said insulation layer above said second magnetic pole.

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- 1 5. (original): A magnetic head as described in claim 4 wherein said heat sink includes a
- 2 first substantial portion that is disposed above said second magnetic pole, and another substantial
- 3 portion that is disposed away from said second magnetic pole.
- 1 6. (original): A magnetic head as described in claim 5 wherein said heat sink is disposed
- 2 away from an air bearing surface of the magnetic head.
- 1 7. (original): A magnetic head as described in claim 1 further including a second heat sink,
- 2 and wherein said heat sink and said second heat sink are thermally interconnected by a heat sink
- 3 interconnect member.
- 1 8. (original): A magnetic head as described in claim 7 wherein said second heat sink is
- 2 disposed below said first magnetic pole.
- 1 9. (original): A magnetic head as described in claim 8 wherein said heat sink is thermally
- 2 interconnected through an interconnect member with a slider body portion of the magnetic head.
- 1 10. (original): A magnetic head as described in claim 8 wherein said heat sink is thermally
- 2 interconnected with said second heat sink through an interconnect member, and said second heat
- 3 sink is thermally interconnected with said slider body through a second interconnect member.
- 1 11. (original): A magnetic head as described in claim 1 wherein said magnetic head is a
- 2 longitudinal head.

- 1 12. (original): A magnetic head as described in claim 1 wherein said magnetic head is a
- 2 perpendicular magnetic head.
- 3 13. (withdrawn): A method for fabricating a magnetic head, comprising:
- 4 fabricating a first magnetic pole;
- 5 fabricating a second magnetic pole;
- fabricating an induction coil, at least in part, between said first magnetic pole and said
- 7 second magnetic pole;
- 8 fabricating an electrical lead to said induction coil;
- 9 fabricating a heat sink member in the same fabrication step in which said electrical lead is
- 10 fabricated.
- 1 14. (withdrawn): A method for fabricating a magnetic head as described in claim 13,
- 2 comprising: fabricating said heat sink in a location above said second magnetic pole.
- 1 15. (withdrawn): A method for fabricating a magnetic head as described in claim 13 wherein
- 2 said electrical lead and said heat sink are fabricated in a photolithographic process.
- 1 16. (withdrawn): A method for fabricating a magnetic head as described in claim 15 wherein
- 2 said photolithographic process includes the use of a mask for forming an electrical lead
- 3 electroplating trench, and said mask also includes an opening for forming a heat sink trench for
- 4 electroplating said heat sink therewithin.

- 1 17. (withdrawn): A method for fabricating a magnetic head as described in claim 13 wherein
- 2 said heat sink includes a first portion that is disposed above said second magnetic pole and a
- 3 second portion that is disposed away from said second magnetic pole.
- 1 18. (withdrawn): A method for fabricating a magnetic head as described in claim 13,
- 2 including the step of fabricating a second heat sink that is disposed below said first magnetic
- 3 pole.
- 1 19. (withdrawn): A method for fabricating a magnetic head as described in claim 18,
- 2 including the step of fabricating a thermal interconnect member between said first heat sink and
- 3 said second heat sink.
- 1 20. (withdrawn): A method for fabricating a magnetic head as described in claim 19,
- 2 including the further step of fabricating a thermal interconnect member between said second heat
- 3 sink and a slider body portion of the magnetic head.
- 4 21. (currently amended): A hard disk drive, comprising:
- 5 at least one hard disk being adapted for rotary motion upon a disk drive;
- at least one slider device having a slider body portion being adapted to fly over said hard
- 7 disk;
- 8 a magnetic head being formed on said slider body for writing data to said hard disk, said
- 9 magnetic head including:
- a write head portion including a first magnetic pole and a second magnetic pole;

- an induction coil being disposed at least in part between said first and second magnetic
- 12 poles;
- an electrical lead of said induction coil <u>having an electrical lead thickness and</u> being
- 14 disposed in a layer of the magnetic head;
- a heat sink being disposed within said layer and being coplanar within the magnetic head
- with said electrical lead of said coil, said heat sink having heat sink thickness that is equal to said
- 17 electrical lead thickness.
- 1 22. (original): A hard disk drive as described in claim 21 wherein said heat sink is disposed
- 2 at least in part upon said second magnetic pole.
- 1 23. (currently amended): A hard disk drive as described in claim 21 wherein said electrical
- 2 lead is fabricated <u>directly</u> upon an insulation layer that is disposed in part above said second
- 3 magnetic pole, and wherein said heat sink is fabricated upon said insulation layer above said
- 4 second magnetic pole.
- 1 24. (original): A hard disk drive as described in claim 21 further including a second heat
- 2 sink, and wherein said heat sink and said second heat sink are thermally interconnected by a heat
- 3 sink interconnect member.
- 1 25. (original): A hard disk drive as described in claim 24 wherein said second heat sink is
- 2 disposed below said first magnetic pole.

- 1 26. (original): A hard disk drive as described in claim 25 wherein said heat sink is thermally
- 2 interconnected through an interconnect member with a slider body portion of the magnetic head.
- 1 27. (original): A hard disk drive as described in claim 25 wherein said heat sink is thermally
- 2 interconnected with said second heat sink through an interconnect member, and said second heat
- 3 sink is thermally interconnected with said slider body through a second interconnect member.